



## SOM-SMARC-QCS5430

SMARC® 2.1.1 module powered by Qualcomm® Dragonwing™ QCS5430 processor

## SMARC® module for high performance low power applications powered by the Dragonwing QCS5430 processor



## HIGHLIGHTS

CPU Qualcomm® Dragonwing™ QCS5430 processor	CONNECTIVITY 2x Gigabit Ethernet
AI ACCELERATOR Embedded AI accelerator (Up to 9 INT8 TOPS)	MEMORY LPDDR5-6400 up to 12GB

Available in Industrial Temperature Range



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## MAIN FIELDS OF APPLICATION



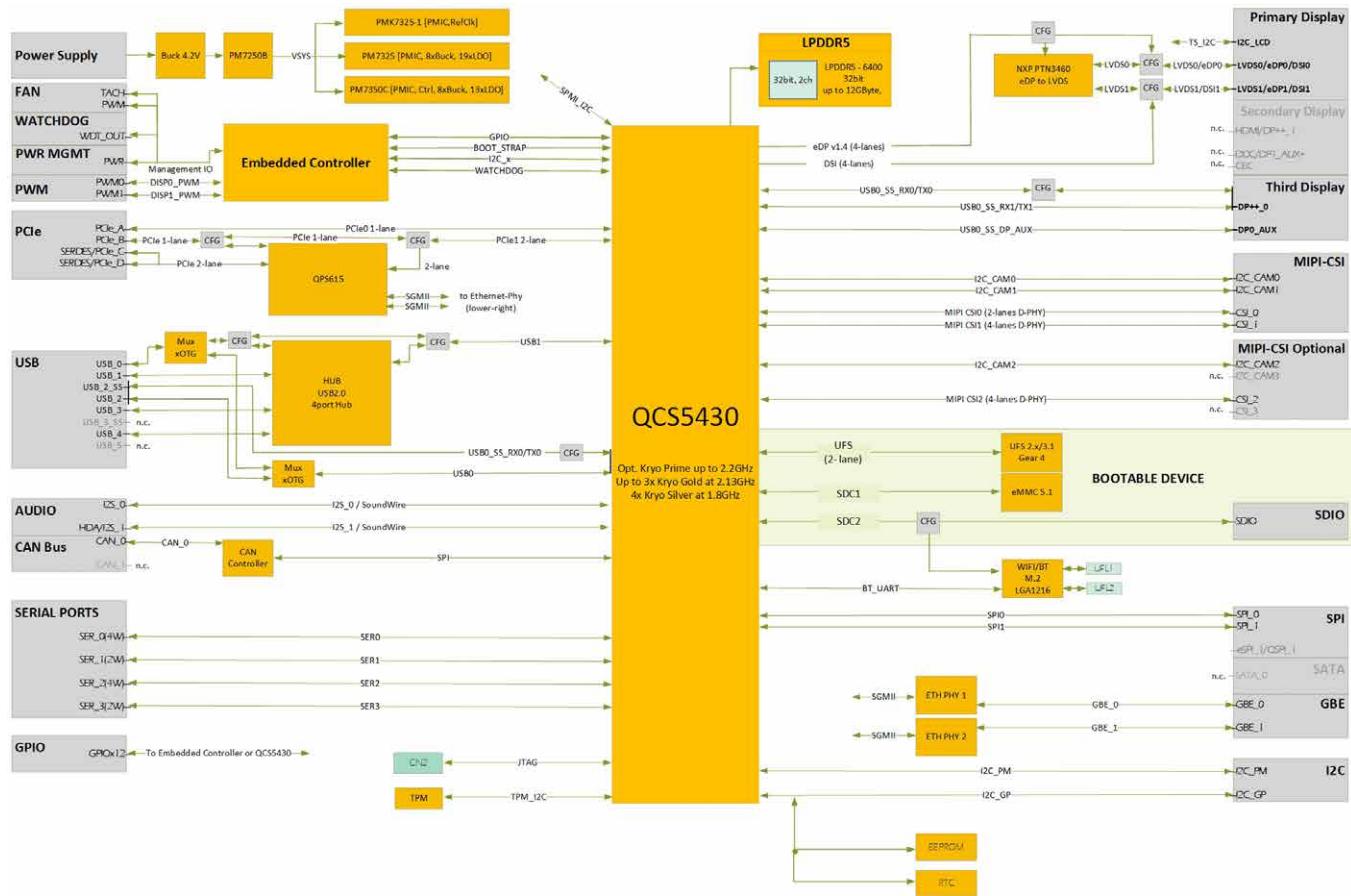
## FEATURES

Processor	Qualcomm® Dragonwing™ QCS5430 FP1/FP2: Opt. Kryo Prime core up to 2.2GHz Up to 3x Kryo Gold cores @ 2.13GHz 4x Low-Power Kryo Silver Cores @1.8GHz  Embedded AI accelerator AI-cDSP up to 9 INT8 TOPS	Serial Ports 2x UART (RX/TX/RTS/CTS), 2x UART (RX/TX)	
Memory	Soldered-down LPDDR5-6400 memory, up to 12GB total, 32-bit interface 2 channels	CAN Bus 1xCAN via SPI	
Video Interfaces	LVDS dual channel 18/24 bit, eDP V1.4, MIPI DSI 4 lanes, Display Port through USB 3.1 Type C	Other Interfaces I2C Ultra Low Power RTC 2xPWM	
Video Resolution	Primary display: FHD+ @120 fps Secondary display: up to 4k Ultra HD @60Hz	Security Optional TPM 2.0 on-board	
Graphics	Qualcomm Adreno™ 642L GPU	Embedded Controller Functionalities FAN Watchdog Power Management I/O Signals	
Mass Storage	eMMC 5.1 drive soldered on-board, up to 64GB (boot device) SD 4-bit interface (boot device) Opt. UFS 2.0/3.1 flash	Power Supply 5V DC (+5V Standby opt)	
Networking	2x Gigabit Ethernet interfaces Opt. Wi-Fi + BT5.0	Operating System Microsoft Windows 11 IoT Enterprise Yocto (Linux 64 Bit) Android	
USB	1x USB 3.1, 1x USB 2.0 OTG, 1x USB 2.0 or 4x USB 2.0 (Hub option)	Operating Temperature* 0 to +60°C (Commercial Range) -30 to +85°C (Industrial Range)	
PCI-e	PCIe lanes Gen3: 2 ports x1 lanes, 1 port x2 lanes (QPS615)	Dimensions 82 x 50 mm	
Camera Interface	2x 4-Line MIPI CSI, with ISP support	*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.	
Audio	2x I2S		

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## BLOCK DIAGRAM



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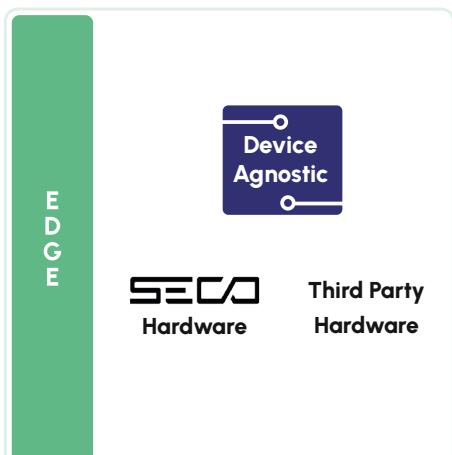
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## Clea Astarte

Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.



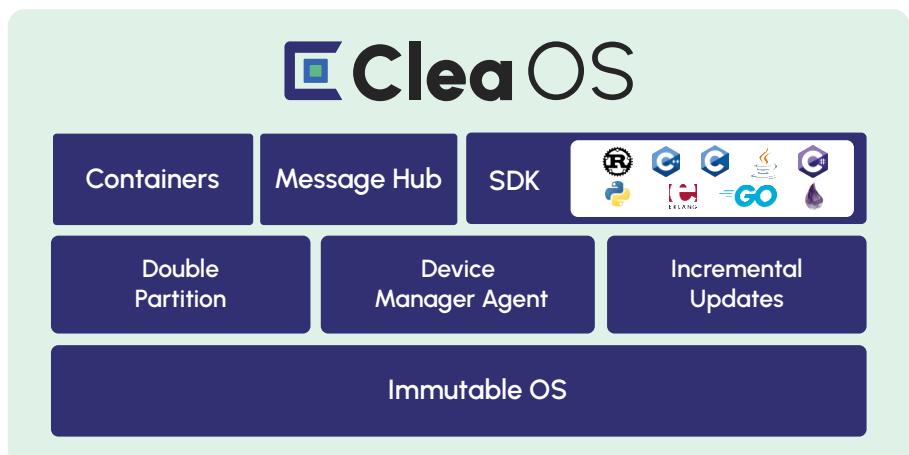
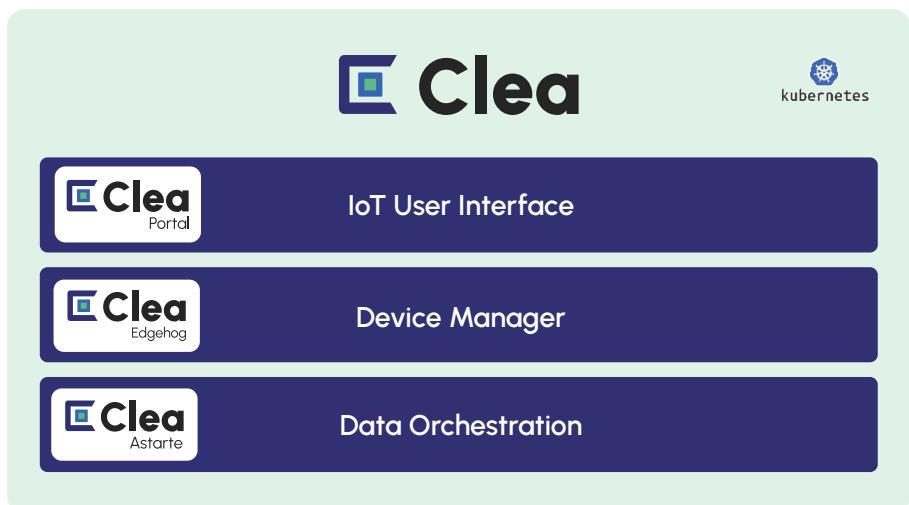
Scan to know more about our solution

## Clea Edgehog

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

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Clea OS



Clea DOCS

